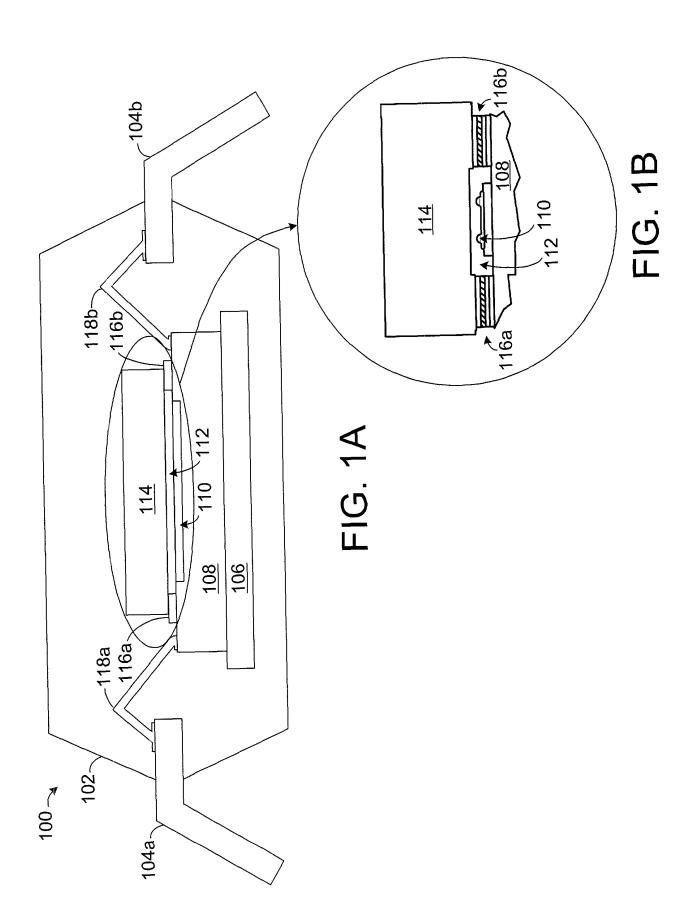
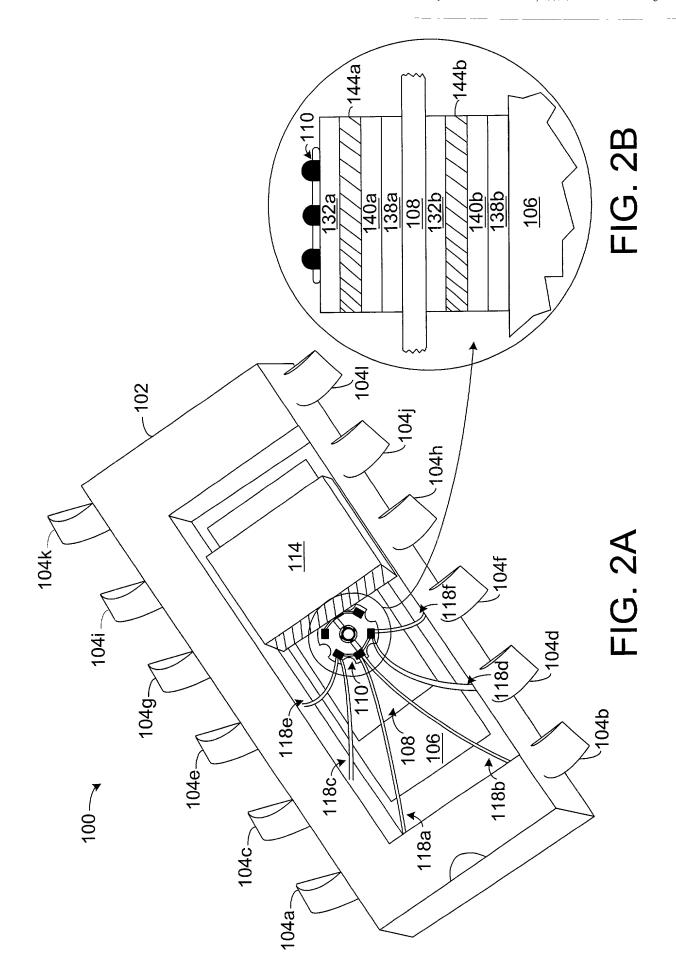
Inventor: William P. Platt
Title: Bonding for a Micro-Electro-Mechanical System (MEMS) and MEMS

Based Devices

Honeywell Case No H0002988, Docket 01-1612

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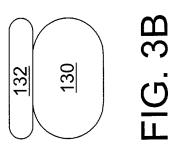


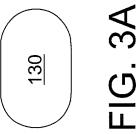


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Based Devices

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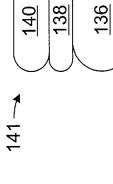
FIG. 3C 134 130 132





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138

136

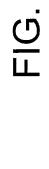


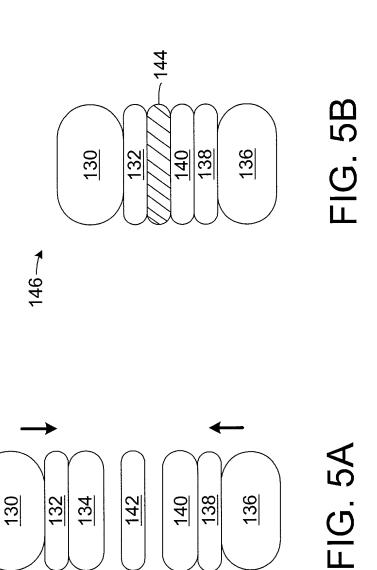
FIG. 4B

Inventor: William P. Platt
Title: Bonding for a Micro-Electro-Mechanical System (MEMS) and MEMS

Based Devices

Honeywell Case No H0002988, Docket. 01-1612





no official rate.

140 Au Diffusion of Au Diffusion of In atoms → ← atoms 144 FIG. 6B 142 _ Diffusion of In Diffusion of Au atoms → ← atoms 144 134 Au Au 140 FIG. 6A In 142 Au 134

142

Based Devices

Honeywell Case No. H0002988, Docket

Inventor: William P. Platt
Title: Bonding for a Micro-Electro-Mechanical System (MEMS) and MEMS

FIG. 7A

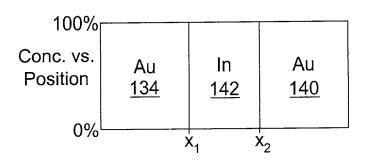


FIG. 8A

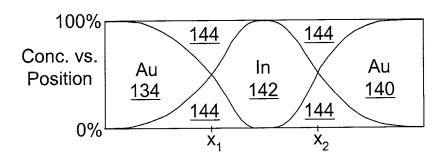


FIG. 8B

142	"1/3 In"	144
134	"2/3 Au"	1

FIG. 8C

FIG. 9

